



Product/Process Change Notice - PCN 13_0192 Rev. A

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This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: AD5748/AD5750/AD5750-1/AD5750-2 Metal Edit and Reduced Package Type

Publication Date: 07-May-2014

Effectivity Date: 05-Aug-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Add Assembly Transfer to ASE-Korea for AD5748, AD5750, AD5750-1 and AD5750-2 products

Description Of Change

The AD5748/AD5750/AD5750-1/AD5750-2 have undergone a minor metal mask edit. The package has been changed from 5mm x 5mm x 0.85mm LFCSP_VQ to 5mm x 5mm x 0.75mm LFCSP_WQ. There is no change in the solder land design.

Rev A April 2014:

ADI is transferring the AD5748, AD5750, AD5750-1 and AD5750-2 products from STATS ChipPAC (STA) (Singapore) to ASE-Korea (ASE-K). This change is due to the new package change as highlighted by PCN 13_0192 Rev-0.

Reason For Change

The metal edit improves electrical overstress (EOS) robustness.
The package change is to adhere to package process standardisation.

Rev A April 2014:

The transfer is due to a new package for the products highlighted in this PCN. The package has been changed from 5mm x 5mm x 0.85mm LFCSP_VQ to 5mm x 5mm x 0.75mm LFCSP_WQ.

Impact of the change (positive or negative) on fit, form, function & reliability

The metal edit will result in an improvement in robustness with regards to power on EOS transients seen in some applications. The height of the package will be reduced from 0.85mm to 0.75mm. Chamfered edges on package will change to 90° edges. No impact to solder land design, function or reliability of parts

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by the modified package and new country of origin (Korea).

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan Summary.

Comments

The new package will be reflected in Rev F. of the AD5750/AD5750-1/AD5750-2 Datasheet and Rev B. of the AD5748 datasheet

Supporting Documents

Attachment 1: Type: Package Outline Drawing

ADI_PCN_13_0192_Rev_A_CP_32_7.pdf

Attachment 2: Type: Qualification Plan Summary

ADI_PCN_13_0192_Rev_A_PCN-13_0192-QP.docx

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models**Existing Parts - Product Family / Model Number (14)**

AD5748 / AD5748ACPZ	AD5748 / AD5748ACPZ-RL7	AD5750 / AD5750ACPZ	AD5750 / AD5750ACPZ-REEL7	AD5750 / AD5750BCPZ
AD5750 / AD5750BCPZ-REEL7	AD5750-1 / AD5750-1ACPZ	AD5750-1 / AD5750-1ACPZ-REEL	AD5750-1 / AD5750-1ACPZ-REEL7	AD5750-1 / AD5750-1BCPZ
AD5750-1 / AD5750-1BCPZ-REEL	AD5750-1 / AD5750-1BCPZ-REEL7	AD5750-2 / AD5750-2BCPZ	AD5750-2 / AD5750-2BCPZ-RL7	

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	24-Feb-2014	20-May-2014	Initial Release
Rev. A	07-May-2014	05-Aug-2014	Add Assembly Transfer to ASE-Korea for AD5748, AD5750, AD5750-1 and AD5750-2 products

Analog Devices, Inc.

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